

Solder paste NO-CLEAN TLF-204-171A, lead-free, for printing processes, 1 cartridge = 600 g

The lead-free solder paste TLF-204-171AK has been developed to meet the requirements of demanding printing processes. The paste offers excellent printing properties, both cold slump and hot slump and thus the formation of unwanted bridges are avoided. Due to the improved activation of the flux, TLF-204-171AK minimises head-in-pillow defects. At the same time, the good activation leads to good wetting on common metallic surfaces. Wetting and solder bead tests as well as contour stability meet the highest requirements. TLF-204-171AK is a NO-CLEAN paste - the residues can remain on the solder joints without causing problems with corrosion or electromigration.

- NO-CLEAN solder paste, lead-free
- for printing processes
- classification ROLO
- metal content 88.5%
- alloy Sn96.5Ag3Cu0.5
- grain size 4 (20-38 µm)
- 1 cartridge = 600 g
- reduction of head-in-pillow Flaws
- High activity on all substrates
- Good wetting on common metallic surfaces
- Excellent printing properties
- Good tack of up to 24h
- Flux classification J-STD-004: ROLO

[<https://www.tamura-elsold.de/index.php/en/downloads/safety-data-sheets-sds>] Please download here the suitable safety data sheet]

item number	WL45185
model	Pastentyp TLF-204-171AK
manufacturer	TAMURA ELSOLD
manufacturer item number	LOTPAST8004
order unit	1 cartridge
content unit	600 g
lead free/containing lead	lead free